Unitrode Products
from Texas Instruments

application INFO available

UC1823
UC2823
UC3823

High Speed PWM Controller

FEATURES

- Compatible with Voltage or Current-Mode Topologies
- Practical Operation @ Switching Frequencies to 1.0MHz
- 50ns Propagation Delay to Output
- High Current Totem Pole Output (1.5A peak)
- Wide Bandwidth Error Amplifier
- Fully Latched Logic with Double Pulse Suppression
- Pulse-by-Pulse Current Limiting
- Soft Start/Max. Duty Cycle Control
- Under-Voltage Lockout with Hysteresis
- Low Start Up Current (1.1mA)
- Trimmed Bandgap Reference (5.1V ±1%)

DESCRIPTION

The UC1823 family of PWM control ICs is optimized for high frequency switched mode power supply applications. Particular care was given to minimizing propagation delays through the comparators and logic circuitry while maximizing bandwidth and slew rate of the error amplifier. This controller is designed for use in either current-mode or voltage-mode systems with the capability for input voltage feed-forward.

Protection circuitry includes a current limit comparator, a TTL compatible shutdown port, and a soft start pin which will double as a maximum duty cycle clamp. The logic is fully latched to provide jitter free operation and prohibit multiple pulses at the output. An under-voltage lockout section with 800mV of hysteresis assures low start up current. During under-voltage lockout, the output is high impedance. The current limit reference (pin 11) is a DC input voltage to the current limit comparator. Consult specifications for details.

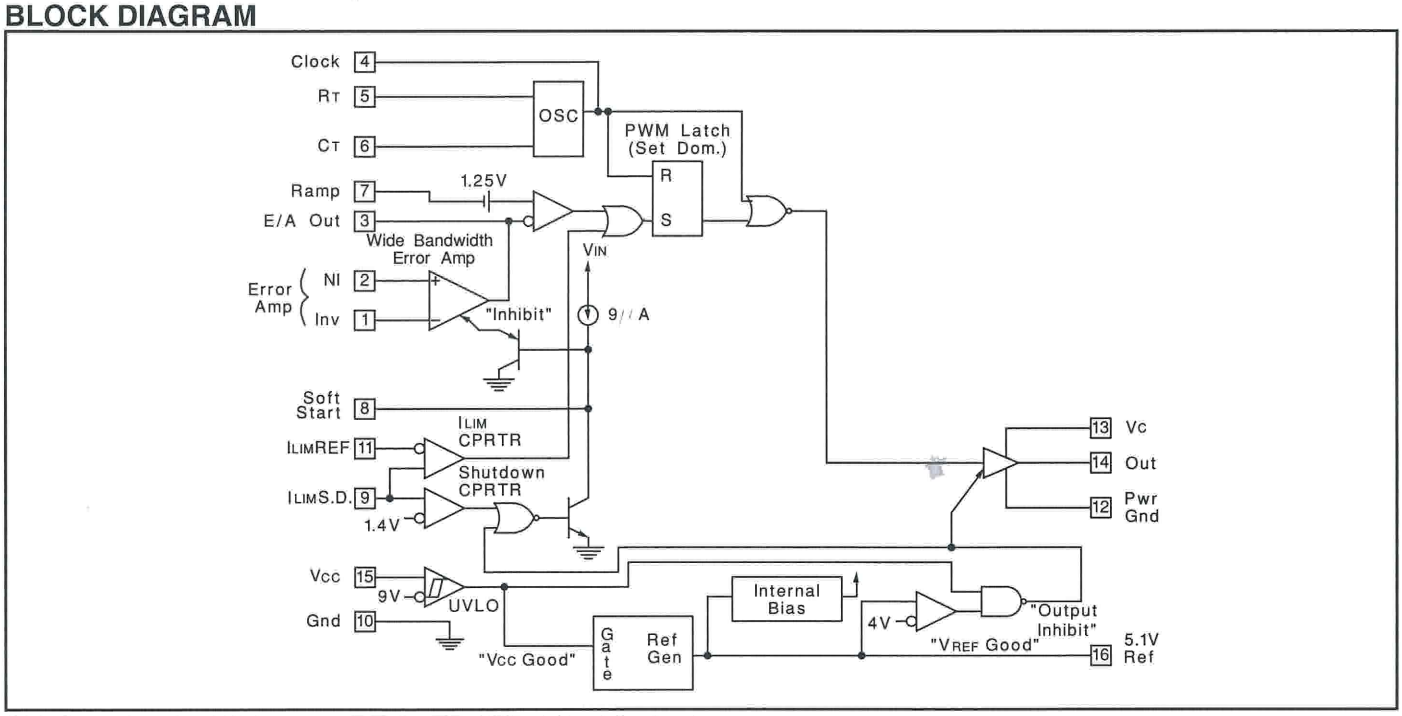
These devices feature a totem pole output designed to source and sink high peak currents from capacitive loads, such as the gate of a power MOSFET. The on state is defined as a high level.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage (Pins 15, 13) 30V
Output Current, Source or Sink (Pin14)
  DC 0.5A
  Pulse (0.5µs) 2.0A
Analog Inputs (Pins 1, 2, 7, 8, 9, 11) . . . . . –0.3V to +6V
Clock Output Current (Pin 4) . . . . . –5mA
Error Amplifier Output Current (Pin 3) 5mA
Soft Start Sink Current (Pin 8) 20mA
Oscillator Charging Current (Pin 5) . . . . . –5mA
Power Dissipation at T_A = 60 °C 1W
Storage Temperature Range . . . . . –65°C to +150°C
Lead Temperature (Soldering, 10 seconds) . . . . . 300°C

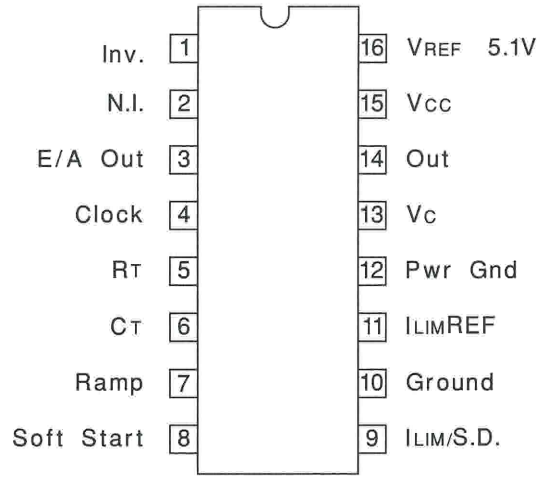
Note: All voltages are with respect to ground, Pin 10.
Currents are positive into the specified terminal.
Consult Packaging Section of Databook for thermal limitations

BLOCK DIAGRAM

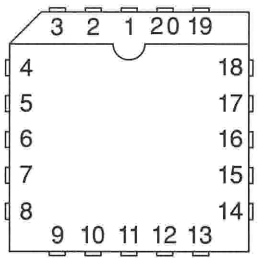


CONNECTION DIAGRAMS

DIL-16, SOIC-16 (TOP VIEW)
J or N, DW Package



PLCC-20, LCC-20 (TOP VIEW)
Q, L Package



PACKAGE PIN FUNCTION	
FUNCTION	**PIN**
N/C	1
Inv.	2
N.I.	3
E/A Out	4
Clock	5
N/C	6
RT	7
CT	8
Ramp	9
Soft start	10
N/C	11
ILIM/S.D.	12
Ground	13
ILIM REF	14
PWR Gnd	15
N/C	16
Vc	17
OUT	18
Vcc	19
VREF 5.1V	20

THERMAL PACKAGING INFORMATION

PACKAGE	θ_{JA}	θ_{JC}
J-16	80 - 120	28 (Note2)
N-16	90 (Note1)	45
DW-16	45 - 90 (Note1)	25
PLCC-20 Q Package	43 - 75 (Note1)	34
LCC-20 LPackage	70 - 80	20 (Note2)

Note 1. Specified θ_{JA} (junction to ambient) is for devices mounted to 5-in-2 FR4 PC board with one ounce copper where noted. When resistance range is given, lower values are for 5-in-2 aluminum PC board. Test PWB was 0.062 in thick and typically used 0.635 mm trace widths for power pkgs and 1.3 mm trace widths for non-power pkgs with a 100 x 100 mil probe land area at the end of each trace.
Note 2. θ_{JC} data values stated were derived from MIL-STD-1835B. MIL-STD-1835B states that "The baseline values shown are worst case (mean + 2s) for a 60 x 60 mil microcircuit device silicon die and applicable for devices with die sizes up to 14400 square mils. For device die sizes greater than14400 square mils use the following values; dual-in-line, 11°C/W; flat pack, 10°C/W; pin grid array, 10°C/W"

ELECTRICAL CHARACTERISTICS: Unless otherwise noted, these specifications apply for R_T = 3.65k, C_T = 1nF, V_{CC} = 15V, 0°C < T_A < +70°C for the UC3823, -25°C < T_A < +85°C for the UC2823, and -55°C < T_A < +125°C for the UC1823, T_A = T_J.

PARAMETER	TEST CONDITIONS	UC1823 UC2823			UC3823			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
Reference Section								
Output Voltage	T_J = 25°C, I_O = 1mA	5.05	5.10	5.15	5.00	5.10	5.20	V
Line Regulation	10 < V_{CC} < 30V		2	20		2	20	mV
Load Regulation	1 < I_O < 10mA		5	20		5	20	mV
Temperature Stability*	T_{MIN} < T_A < T_{MAX}		0.2	0.4		0.2	0.4	mV/°C
Total Output Variation*	Line, Load, Temp.	5.00		5.20	4.95		5.25	
Output Noise Voltage*	10Hz < f < 10kHz		50			50		µV
Long Term Stability*	T_J = 125°C, 1000 hrs.		5	25		5	25	mV
Short Circuit Current	V_{REF}=0V	-15	-50	-100	-15	-50	-100	mA
Oscillator Section								
Initial Accuracy*	T_J=25°C	360	400	440	360	400	440	kHz
Voltage Stability*	10 < V_{CC} < 30V		0.2	2		0.2	2	%
Temperature Stability*	T_{MIN} <T_A < T_{MAX} (UC1823)		12					%
	T_{MIN} <T_A < T_{MAX} (UC2823)		5					%
	T_{MIN} <T_A < T_{MAX} (UC3823)					5		%
Total Variation*	Line, Temp.	340		460	340		460	kHz
Clock Out High		3.9	4.5		3.9	4.5		V
Clock Out Low			2.3	2.9		2.3	2.9	V
Ramp Peak*		2.6	2.8	3.0	2.6	2.8	3.0	V
Ramp Valley*		0.7	1.0	1.25	0.7	1.0	1.25	V
Error Amplifier Section								
Input Offset Voltage				10			15	mV
Input Bias Current			0.6	3		0.6	3	µA
Input Offset Current			0.1	1		0.1	1	µA
Open Loop Gain	1 < V_O < 4V	60	95		60	95		dB
CMRR	1.5 < V_{CM} < 5.5V	75	95		75	95		dB
PSRR	10 < V_{CC} < 30V	85	110		85	110		dB
Output Sink Current	$V_{PIN\ 3}$ =1V	1	2.5		1	2.5		mA
Output Source Current	$V_{PIN\ 3}$ = 4V	-0.5	-1.3		-0.5	-1.3		mA
Output High Voltage	$I_{PIN\ 3}$ = –0.5mA	4.0	4.7	5.0	4.0	4.7	5.0	V
Output Low Voltage	$I_{PIN\ 3}$ = 1mA	0	0.5	1.0	0	0.5	1.0	V
Unity Gain Bandwidth*		3	5.5		3	5.5		MHz
Slew Rate*		6	12		6	12		V/µS
Ramp Valley to Peak*		1.6	1.8	2.0	1.6	1.8	2.0	V

* These parameters are ensured by design but not 100% tested in production.

ELECTRICAL CHARACTERISTICS: Unless otherwise noted, these specifications apply for R_T = 3.65k, C_T = 1nF, V_{CC} = 15V, 0°C < T_A < +70°C for the UC3823, -25°C < T_A < +85°C for the UC2823, and -55°C < T_A < +125°C for the UC1823, T_A = T_J.

PARAMETER	TEST CONDITIONS	UC1823 UC2823			UC3823			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
PWM Comparator Section								
Pin 7 Bias Current	$V_{PIN\ 7}$ = 0V		-1	-5		-1	-5	µA
Duty Cycle Range		0		80	0		85	%
Pin 3 Zero D.C. Threshold	$V_{PIN\ 7}$ = 0V	1.1	1.25		1.1	1.25		V
Delay to Output*			50	80		50	80	ns
Soft-Start Section								
Charge Current	$V_{PIN\ 8}$ = 0.5V	3	9	20	3	9	20	µA
Discharge Current	$V_{PIN\ 8}$ = 1V	1			1			mA
Current Limit/Shutdown Section								
Pin 9 Bias Current	0 < $V_{PIN\ 9}$ < 4V			±10			±10	µA
Current Limit Offset	$V_{PIN\ 11}$ = 1.1V			15			15	mV
Current Limit Common Mode Range ($V_{PIN\ 11}$)		1.0		1.25	1.0		1.25	V
Shutdown Threshold		1.25	1.40	1.55	1.25	1.40	1.55	V
Delay to Output*			50	80		50	80	ns
Output Section								
Output Low Level	I_{OUT} = 20mA		0.25	0.40		0.25	0.40	V
	I_{OUT} = 200mA		1.2	2.2		1.2	2.2	V
Output High Level	I_{OUT} = –20mA	13.0	13.5		13.0	13.5		V
	I_{OUT} = –200mA	12.0	13.0		12.0	13.0		V
Collector Leakage	V_C = 30V		100	500		100	500	µA
Rise/Fall Time*	C_L = 1nF		30	60		30	60	ns
Under-Voltage Lockout Section								
Start Threshold		8.8	9.2	9.6	8.8	9.2	9.6	V
UVLO Hysteresis		0.4	0.8	1.2	0.4	0.8	1.2	V
Supply Current								
Start Up Current	V_{CC} = 8V		1.1	2.5		1.1	2.5	mA
I_{CC}	$V_{PIN\ 1}$, $V_{PIN\ 7}$, $V_{PIN\ 9}$ =0V, $V_{PIN\ 2}$ = 1V		22	33		22	33	mA

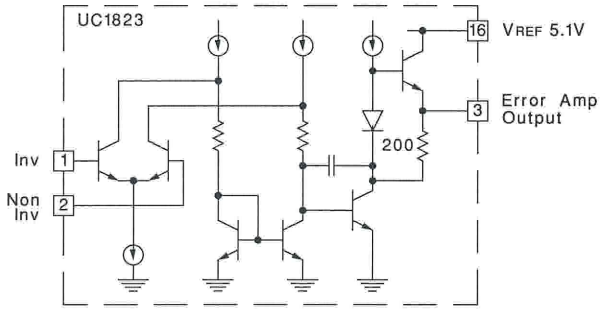
* These parameters are ensured by design but not 100% tested in production.

UC1823 PRINTED CIRCUIT BOARD LAYOUT CONSIDERATIONS

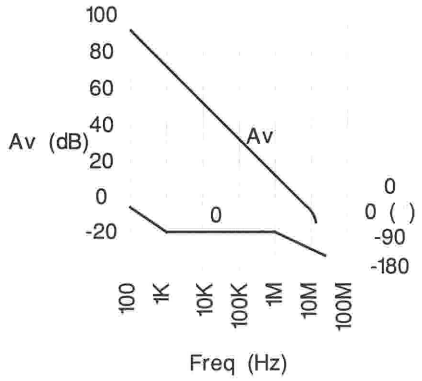
High speed circuits demand careful attention to layout and component placement. To assure proper performance of the UC1823, follow these rules. 1) Use a ground plane. 2) Damp or clamp parasitic inductive kick energy from the gate of driven MOSFET. Don't allow the output pins to ring below ground. A series gate resistor or a shunt 1 Amp Schottky diode at the output pin will serve this purpose. 3) Bypass V_{CC}, V_C, and V_{REF}. Use 0.1µF monolithic ceramic capacitors with low equivalent series inductance. Allow less than 1 cm of total lead length for each capacitor between the bypassed pin and the ground plane. 4) Treat the timing capacitor, C_T, like a bypass capacitor.

ERROR AMPLIFIER CIRCUIT

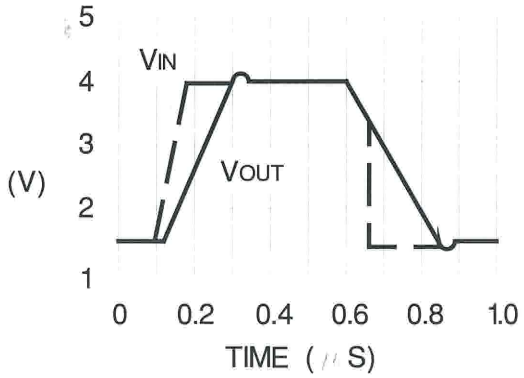
Simplified Schematic



Open Loop Frequency Response

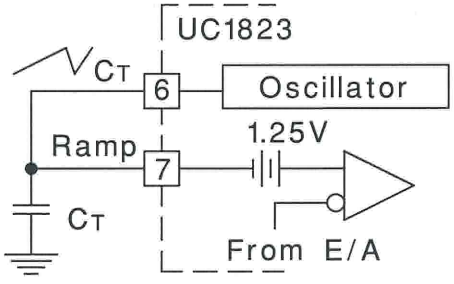


Unity Gain Slew Rate

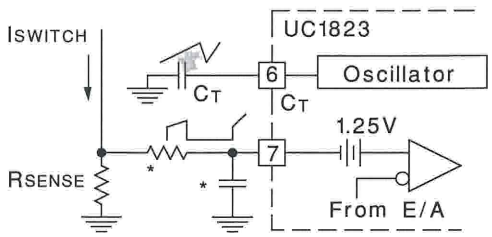


PWM APPLICATIONS

Conventional (Voltage Mode)

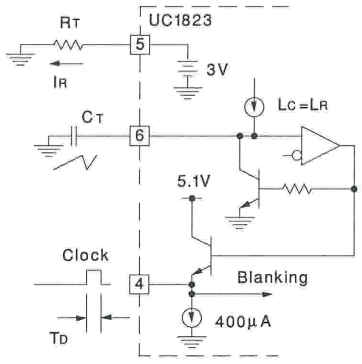


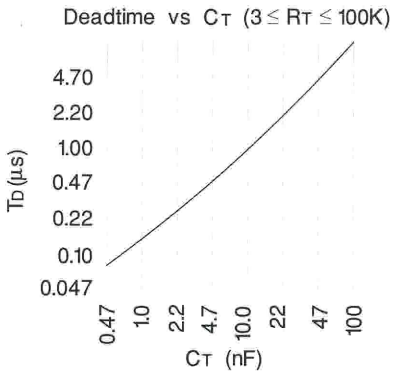
Current-Mode

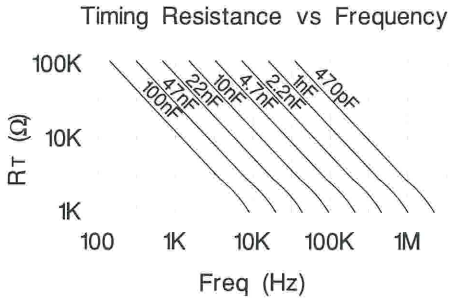


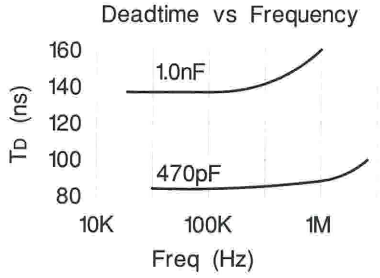
* A small filter may be required to suppress switch noise

OSCILLATOR CIRCUIT



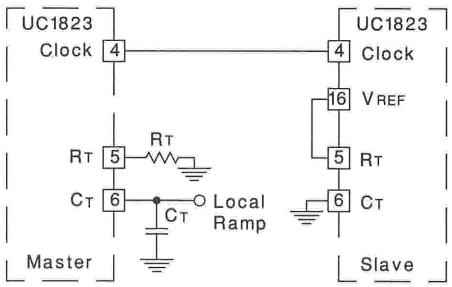




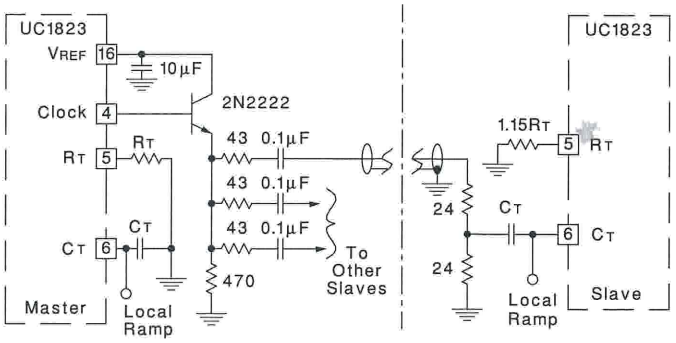


SYNCHRONIZED OPERATION

Two Units in Close Proximity

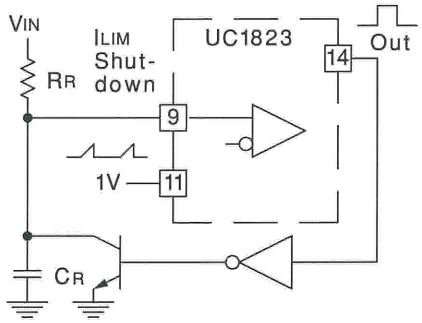


Generalized Synchronization

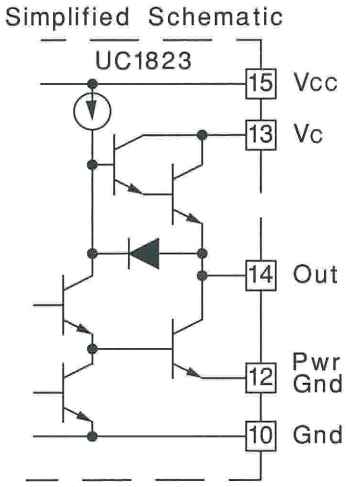


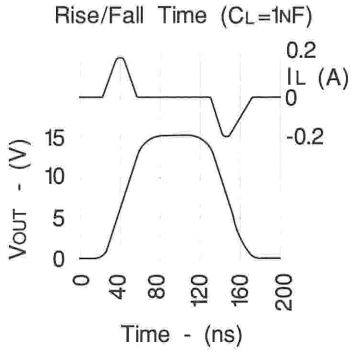
CONSTANT VOLT-SECOND CLAMP CIRCUIT

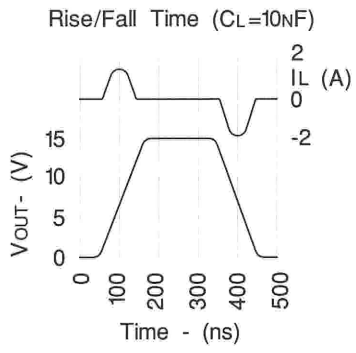
The circuit shown here will achieve a constant volt-second product clamp over varying input voltages. The ramp generator components, R_T and C_R are chosen so that the ramp at Pin 9 crosses the 1V threshold at the same time the desired maximum volt-second product is reached. The delay through the inverter must be such that the ramp capacitor can be completely discharged during the minimum deadtime.

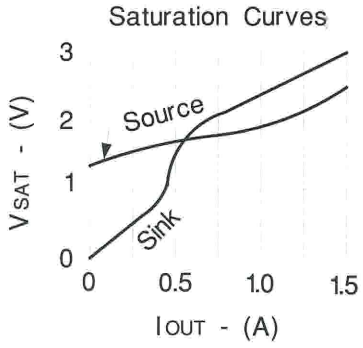


OUTPUT SECTION

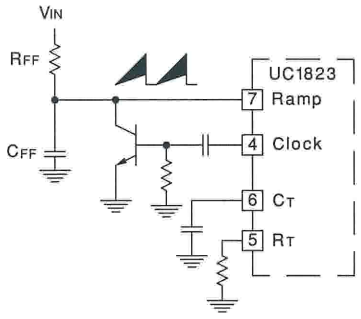








FEED FORWARD TECHNIQUE FOR OFF-LINE VOLTAGE MODE APPLICATION



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-89905012A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-89905012A UC1823L/ 883B
5962-8990501EA	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8990501EA UC1823J/883B
UC1823J	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1823J
UC1823J.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1823J
UC1823J883B	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8990501EA UC1823J/883B
UC1823J883B.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8990501EA UC1823J/883B
UC1823L	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1823L
UC1823L.A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1823L
UC1823L883B	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-89905012A UC1823L/ 883B
UC1823L883B.A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-89905012A UC1823L/ 883B
UC2823DW	Active	Production	SOIC (DW) | 16	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-25 to 85	UC2823DW
UC2823DW.A	Active	Production	SOIC (DW) | 16	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-25 to 85	UC2823DW
UC2823DWTR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-25 to 85	UC2823DW
UC2823DWTR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-25 to 85	UC2823DW
UC2823N	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-25 to 85	UC2823N
UC2823N.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-25 to 85	UC2823N
UC3823DW	Active	Production	SOIC (DW) | 16	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3823DW
UC3823DW.A	Active	Production	SOIC (DW) | 16	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3823DW
UC3823DWG4	Active	Production	SOIC (DW) | 16	40 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3823DW
UC3823DWTR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3823DW

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
UC3823DWTR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3823DW
UC3823N	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3823N
UC3823N.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3823N
UC3823NG4	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3823N

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF UC1823, UC3823 :

- Catalog : UC3823

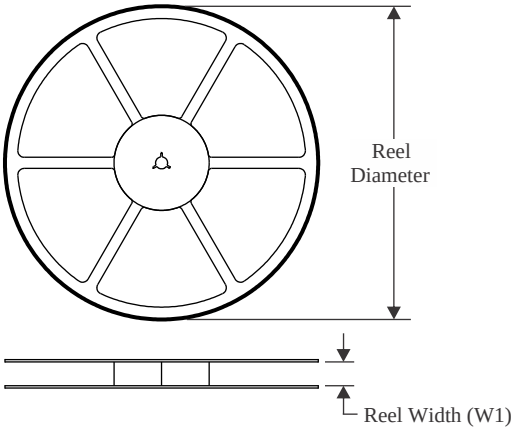
- Military : UC1823

NOTE: Qualified Version Definitions:

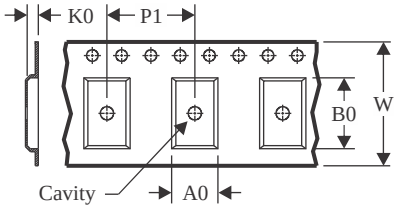
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

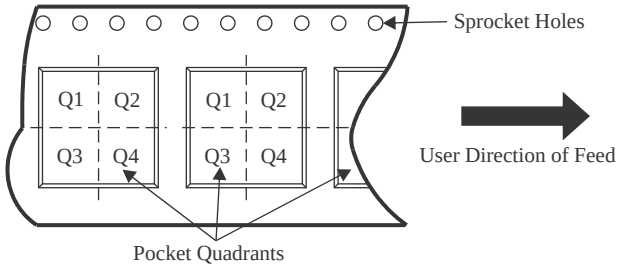


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

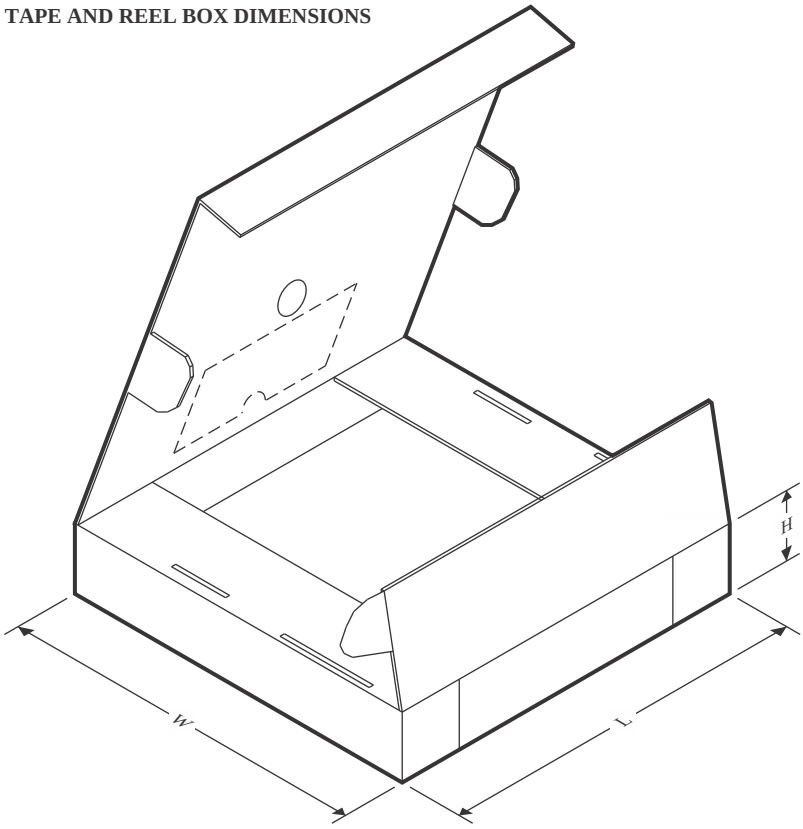
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2823DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
UC3823DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

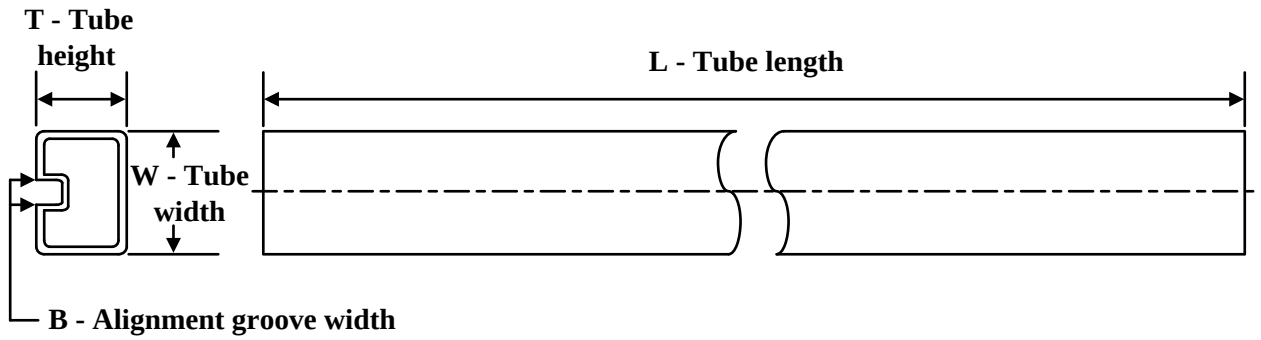
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2823DWTR	SOIC	DW	16	2000	353.0	353.0	32.0
UC3823DWTR	SOIC	DW	16	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-89905012A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1823L	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1823L.A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1823L883B	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1823L883B.A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC2823DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC2823DW.A	DW	SOIC	16	40	507	12.83	5080	6.6
UC2823N	N	PDIP	16	25	506	13.97	11230	4.32
UC2823N.A	N	PDIP	16	25	506	13.97	11230	4.32
UC3823DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC3823DW.A	DW	SOIC	16	40	507	12.83	5080	6.6
UC3823DWG4	DW	SOIC	16	40	507	12.83	5080	6.6
UC3823N	N	PDIP	16	25	506	13.97	11230	4.32
UC3823N.A	N	PDIP	16	25	506	13.97	11230	4.32
UC3823NG4	N	PDIP	16	25	506	13.97	11230	4.32

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